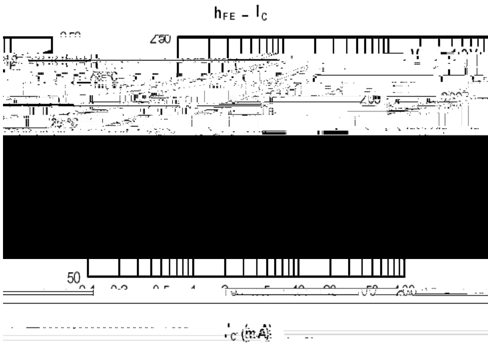
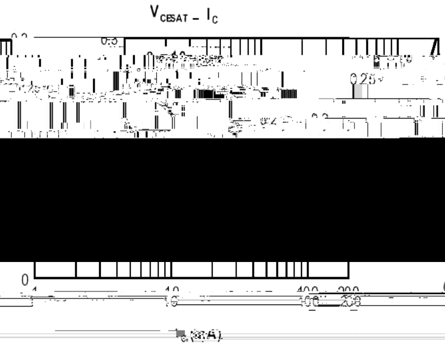
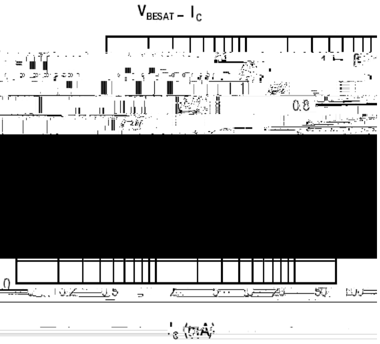
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-200	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

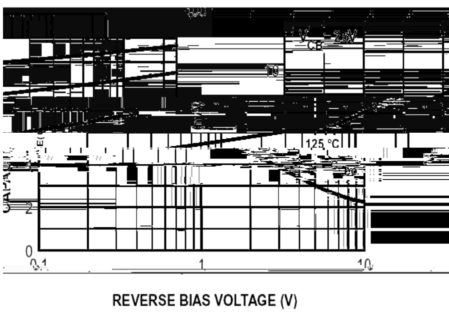
Parameter	Symbol	Test Conditions	Min	T

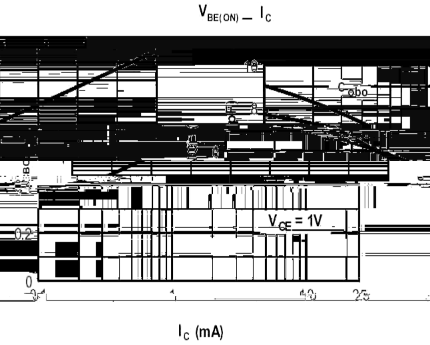
/ Electrical Characteristic Curve

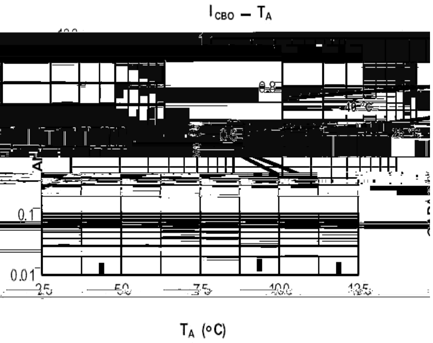


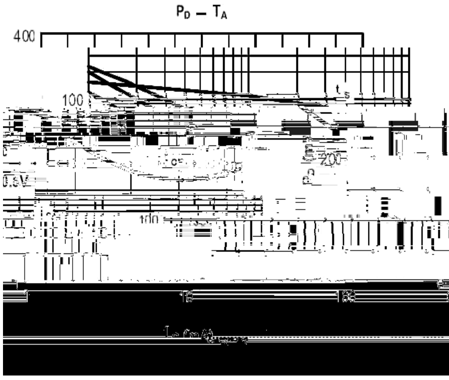


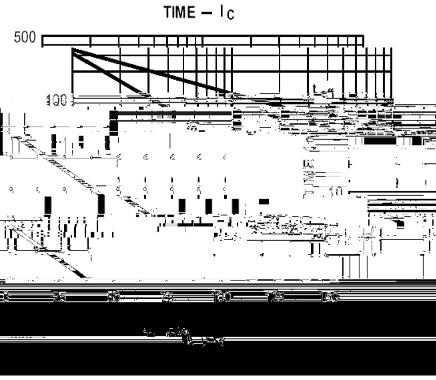


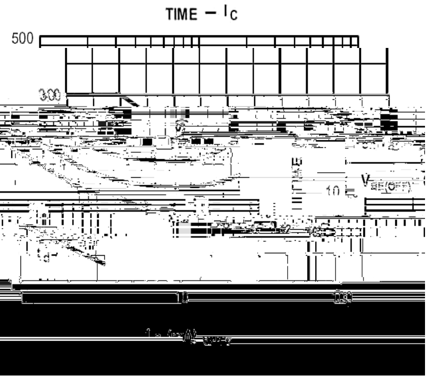




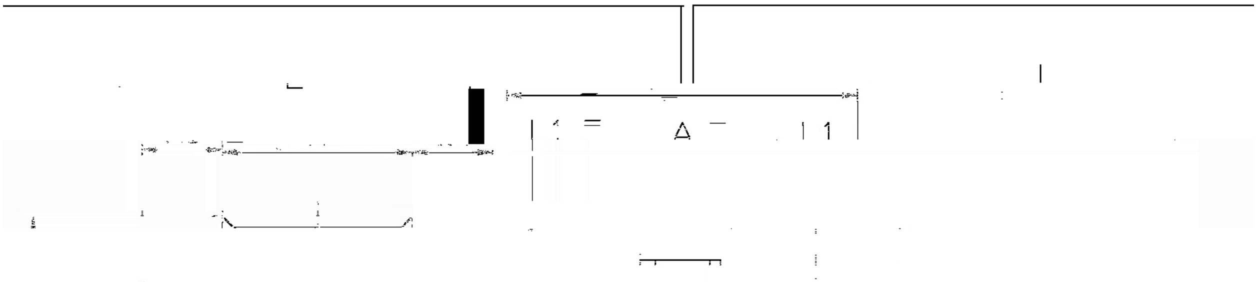






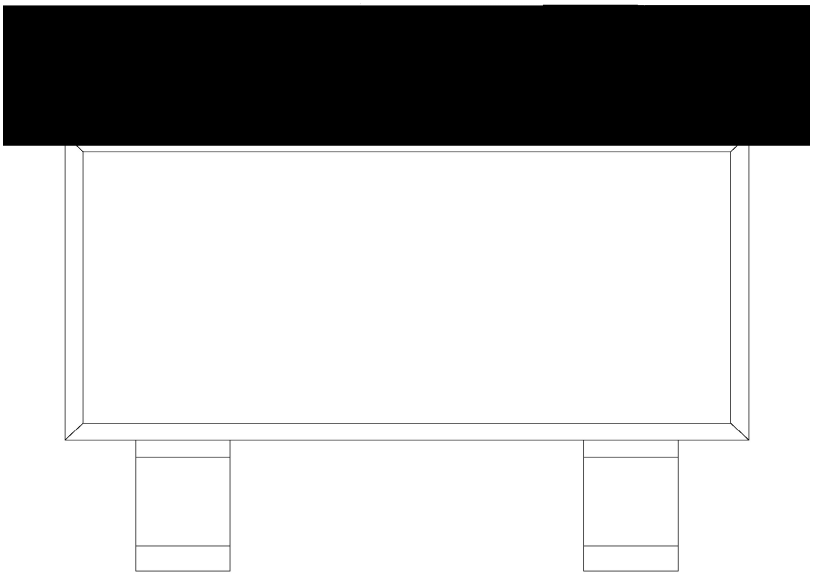


/ Package Dimensions

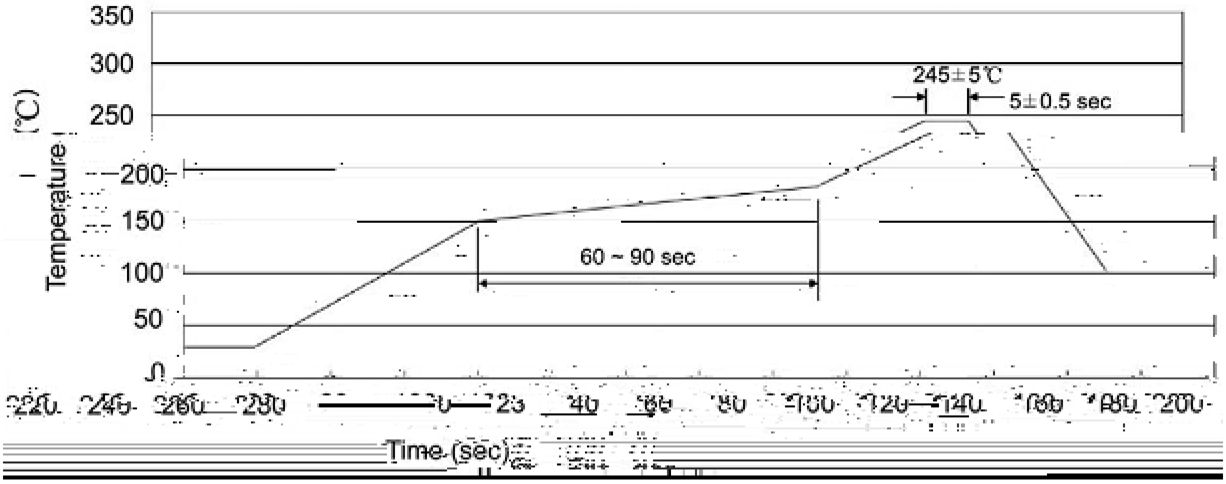


Dim	Min	Max	Symbol	Min	Max
[illegible]	0.45	0.65	[illegible]	0.82	[illegible]
A	1.15	1.50	C	0.05	0.20
B	2.72	[illegible]	K	0	[illegible]
[illegible]	7°	[illegible]	[illegible]	0.85	[illegible]
[illegible]	[illegible]	[illegible]	[illegible]	0.35	0.55

[redacted]



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



	Note:
1 25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5℃	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type !	Units " # $	Dimension " % & (unit ' mm^3)